

A¹ cont. 1 is replaced by the volume of material 19 of FIG. 23. The volume of material 19 of FIG. 23 may include any material (e.g., a nonsolderable and nonconductive material such as a polyimide or a photosensitive resin) that could be included in the coat of material 18 of FIG. 1, or additionally epoxy adhesive or silicone adhesive. The first substrate 12 (e.g., chip, module), first conductive bodies 14 (e.g., solder bump such as C4 solder ball), and pads 16 in FIG. 23 are the same as in FIG. 1. All processes, materials, etc. described *supra* for FIG. 1 apply to FIG. 23 except for differences attributable to the geometrical difference between the volume of material 19 of FIG. 23 and the coat of material 18 of FIG. 1. The volume of material 19 is said to volumetrically surround the conductive bodies 14. As seen in FIGS. 23-28, the volume of material 19 is continuously distributed between the two first conductive bodies 14 shown in FIGS. 23-28, and the volume of material 19 fills a space between the two first conductive bodies 14 shown in FIGS. 23-28.

In The Claims

Currently pending claims 1-18 and 40-41 are as follows based on the amendment herein, wherein claims 1 and 18 have been amended, and wherein claims 40 and 41 are new:

1. (AMENDED) An electrical structure, comprising:

- A²
- a first substrate;
 - a first conductive body mechanically and electrically coupled to the first substrate;
 - a third conductive body mechanically and electrically coupled to the first substrate;
 - a nonsolderable and nonconductive material, wherein the nonsolderable and nonconductive material volumetrically surrounds and contacts a first portion of a surface of the